Docket No. 242859US0DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Hitoshi SAKAMOTO, et al.

SERIAL NO: NEW APPLICATION GAU:

FILED: HEREWITH EXAMINER:

FOR: HEXAGONAL BORON NITRIDE FILM WITH LOW DIELECTRIC CONSTANT, LAYER DIELECTRIC FILM

AND METHOD OF PRODUCTION THEREOF, AND PLASMA CVD APPARATUS

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references were filed on June 15, 2001, November 29, 2001and were also entered by the U.S. Patent Office on December 18, 2002 and June 20, 2003 in U.S. Application Serial No. 09/880,932 filed June 15, 2001, pending, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- □ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number <u>15-0030</u>. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

Norman F. Oblon

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Customer Number

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Vincent K. Shier, Ph.D. Registration No. 50,552 Docket No. 242859US0DIV

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Form PTO 1449 U.S. DEPARTMENT OF COMMERCE (Modified) PATENT AND TRADEMARK OFFICE			ATTY DOCKET NO.		SERIAL NO.					
			242859US0DIV	NEW APPLICATION						
				APPLICANT						
LIST OF	REFE	RENCES CITED BY AP	PLICANT	Hitoshi SAKAMOTO, et al.						
				FILING DATE		GROUP				
				HEREWITH						
				U.S. PATENT DOCUMENTS						
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE			
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